IN THE CLAIMS:

1. (Original) A curable silicone composition comprising:

(A) an organopolysiloxane represented by the siloxane unit formula (1) given below and having at least two univalent organic groups that contain epoxy groups and are free of aromatic rings:

$$[R^1{}_3SiO_{1/2}]_a[R^2{}_2SiO_{2/2}]_b[R^3SiO_{3/2}]_c \qquad (1)$$

where R^1, R^2, and R^3 are univalent organic groups, at least two of which are univalent organic groups which contain epoxy groups and are free of aromatic rings; more than 20 mole % of R^3 are aryl groups; $a + b + c = 1$; on average, "a" satisfies the following condition: $0 \leq a \leq 0.8$; on average, "b" satisfies the following condition: $0 \leq b \leq 0.8$; and, on average, "c" satisfies the following condition: $0.2 \leq c \leq 1.0$;

(B) a linear-chain organopolysiloxane having at least two univalent organic groups that contain phenolic hydroxyl groups; and

(C) a curing accelerator.

2. (Original) The curable silicone composition of Claim 1, further comprising a filler (D).

3. (Currently Amended) The curable silicone composition of Claim 1 ~~or Claim 2~~, where component (A) is liquid.

4. (Currently Amended) The curable silicone composition of Claim 1 ~~or Claim 2~~, where in the siloxane unit formula (1), $0 < a \leq 0.8$; and b=0.

5. (Currently Amended) The curable silicone composition of Claim 1 ~~or Claim 2~~, where component (B) is an organopolysiloxane represented by the following formula (2):

$R^7{}_3SiO(R^8{}_2SiO)_mSiR^7{}_3$ (2)

where R^7 and R^8 may be the same or different and represent univalent organic groups of which, at least two are univalent organic groups having phenolic hydroxyl groups; and "m" is an integer having a value of 0 to 1000~~]~~.

6. (Currently Amended) The curable silicone composition of Claim 1 ~~or Claim 2~~, where component (B) is an organopolysiloxane represented by the following formula (4):

$Z\text{-}(CH_3)_2SiO(CH_3)_2Si\text{-}Z$ (4)

where Z is 3-(m-hydroxyphenyl)propyl group.

7. (Currently Amended) The curable silicone composition of Claim 1 ~~or Claim 2~~, where component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) in an amount of 0.01 to 100 parts by weight for each 100 parts by weight of component (A).

8. (Currently Amended) The curable silicone composition of Claim 1 ~~or Claim 2~~, where the epoxy group of component (A) is a glycidoxy group or a 2,4-epoxycyclohexyl group.

9. (Currently Amended) The curable silicone composition of Claim 1 ~~or Claim 2~~, which is in a liquid or a paste-like form.

10. (Currently Amended) A cured product obtained by curing the curable silicone composition according to ~~any of Claims from 1 to 9~~ Claim 1.

11. (Original) Use of the cured product according to Claim 10 for connection or sealing of elements in an electric or electronic device.

Please add the following new claims.

12. (New) The curable silicone composition of Claim 2, where component (A) is liquid.

13. (New) The curable silicone composition of Claim 2, where in the siloxane unit formula (1), $0 < a \leq 0.8$; and b=0.

14. (New) The curable silicone composition of Claim 2, where component (B) is an organopolysiloxane represented by the following formula (2):

$$R^7{}_3SiO(R^8{}_2SiO)_mSiR^7{}_3 \qquad (2)$$

where R^7 and R^8 may be the same or different and represent univalent organic groups of which, at least two are univalent organic groups having phenolic hydroxyl groups; and "m" is an integer having a value of 0 to 1000.

15. (New) The curable silicone composition of Claim 2, where component (B) is an organopolysiloxane represented by the following formula (4):

$$Z\text{-}(CH_3)_2SiO(CH_3)_2Si\text{-}Z \qquad (4)$$

where Z is 3-(m-hydroxyphenyl)propyl group.

16. (New) The curable silicone composition of Claim 2, where component (B) is used in an amount of 1 to 1000 parts by weight, and component (C) in an amount of 0.01 to 100 parts by weight for each 100 parts by weight of component (A).

17. (Currently Amended) The curable silicone composition of Claim 2, where the epoxy group of component (A) is a glycidoxy group or a 2,4-epoxycyclohexyl group.

18. (Currently Amended) The curable silicone composition of Claim 2, which is in a liquid or a paste-like form.